DESCRIPTION:

The products are 10MBd high-speed opto-couplers in a plastic WSOP8 package. The device consists of a high efficient AlGaAs Light Emitting Diode and a high speed optical detector. This design provides excellent AC and DC isolation between the input and output sides of the optocoupler. The output of the optical detector features an open collector Schottky clamped transistor. The ct] Ņ o "

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	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	-	10^{12}	-	Ω
	Floating Capacitance	C_{IO}	V=0, f=1MHz	-	1	-	pF
Switching Characteristics	Trigger LED Current	I_{FT}	V_{CC}=5V V_O=V_{OL}	-	-	5	mA
	Propagation Delay Time to Logic Low	t_{PHL}	C_L=15pF, R_L=350Ω, I_F=7.5mA	-	-	60	ns
	Propagation Delay Time to Logic High	t_{PLH}		-	-	60	ns
	Pulse width distortion	$\|t_{PHL}-t_{PLH}\|$		-	-	35	ns
	Common Mode Transient Immunity at Logic High	CM_H	V_{CC}=3.3V, I_F=0mA, V_{CM}=1000V, R_L=350Ω	10	15	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	V_{CC}=3.3V, I_F=10mA, V_{CM}=1000V, R_L=350Ω	10	15	-	kV/μs
	Rise Time	tr	C_L=15pF, R_L=350Ω, I_F=7.5mA	-	30	-	ns
	Fall Time	tf		-	30	-	ns

Recommended Operating Conditions

Operating Temperature	T_a	-40	-	85	
Supply Voltage	V_{CC}	2.7	-	3.6	V

VV

Output Pull-up Resistor	R_L	330	-	4k	Ω
Fan Out (at R_L=1kΩ per channel)	N	-	-	5	TTL Loads

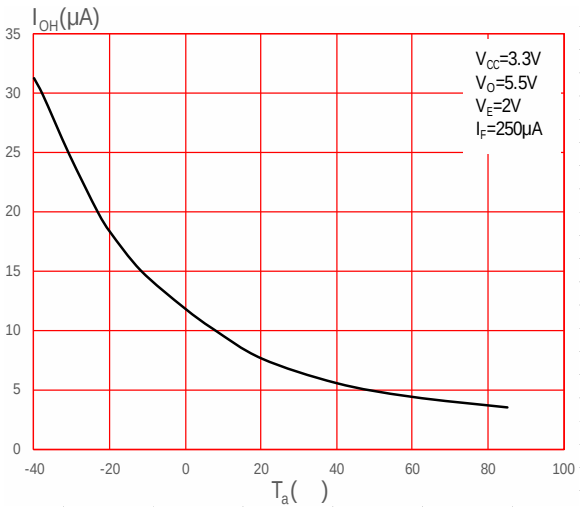
ORDERING INFORMATION

J OC H A 1 4 B -W8 /

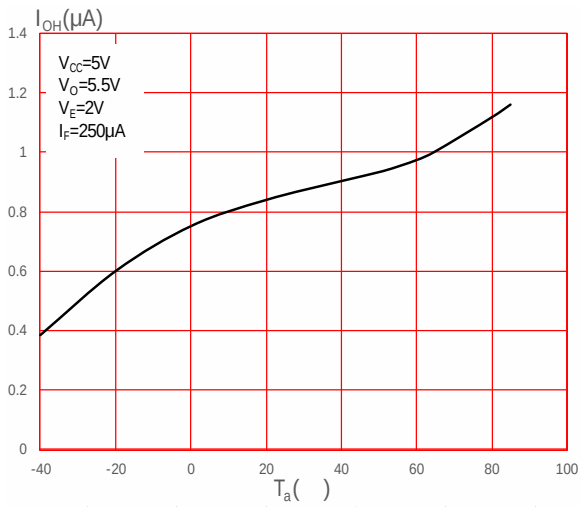
JieJie Microelectronics Co., Ltd.

Characteristics Curves

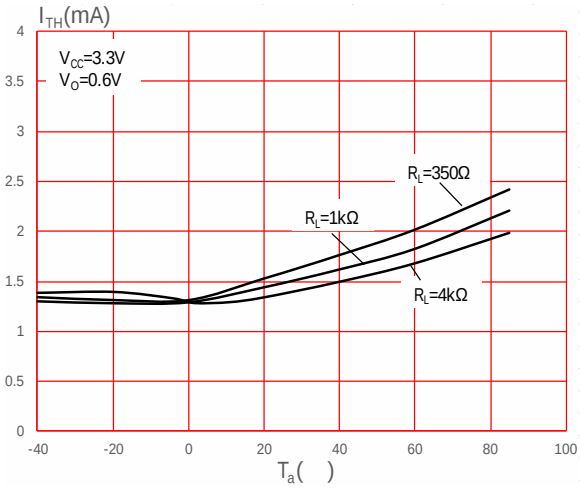
High Level Output Current vs. Ambient Temperature



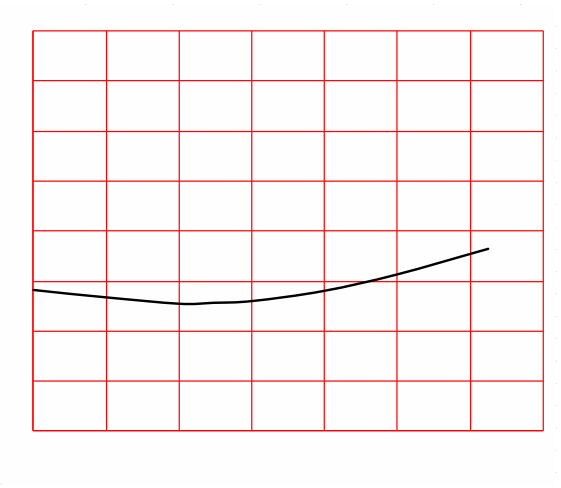
High Level Output Current vs. Ambient Temperature



Input Threshold Current vs. Ambient Temperature



Input Threshold Current vs. Ambient Temperature



Package Dimension (Un

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
B	6.15		6.35	0.242		0.250
C			0.53			0.021
D	3.50		3.70			0.146
E	14.71		15.31			0.603
F						
G	16.36		16.86			0.664
H	0.10		0.40			0.016
I	3.65			0.144		
K						

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1